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(54) Title: DIELECTRIC FILM-FORMING COMPOSITION

(57) Abstract: This disclosure relates to a dielectric film-forming composition that includes (a) at least one meth(acrylate)-containing polyphenylene ether resin and (b) at least one second resin selected from the group consisting of: i) at least one fully imidized polyimide polymer; ii) at least one polyamic acid ester; iii) at least one cyclized polydiene resin; and iv) a mixture of a cyclized polydiene resin and a cyanate ester compound.

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